Silicon NPN Epitaxial

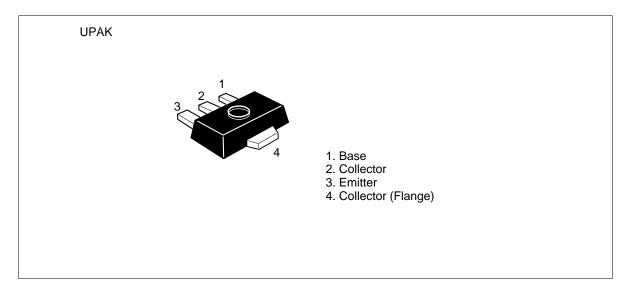
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ADE-208-1147 (Z) 1st. Edition Mar. 2001

Application

- Low frequency power amplifier
- Complementary pair with 2SB1001

Outline





Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	20	V
Collector to emitter voltage	V _{CEO}	16	V
Emitter to base voltage	V _{EBO}	6	V
Collector current	I _c	2	A
Collector peak current	i _{C(peak)} *1	3	A
Collector power dissipation	P _c * ²	1	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. $PW \le 10 \text{ ms}$, $Duty cycle \le 20\%$.

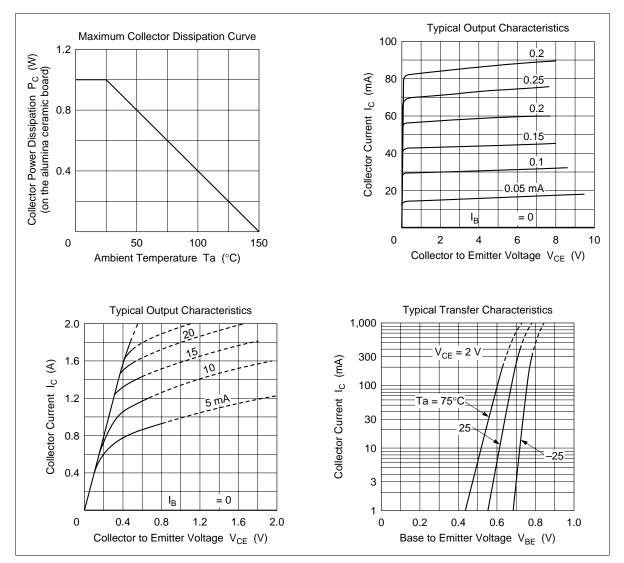
2. Value on the alumina ceramic board (12.5 \times 20 \times 0.7 mm)

Electrical Characteristics (Ta = 25°C)

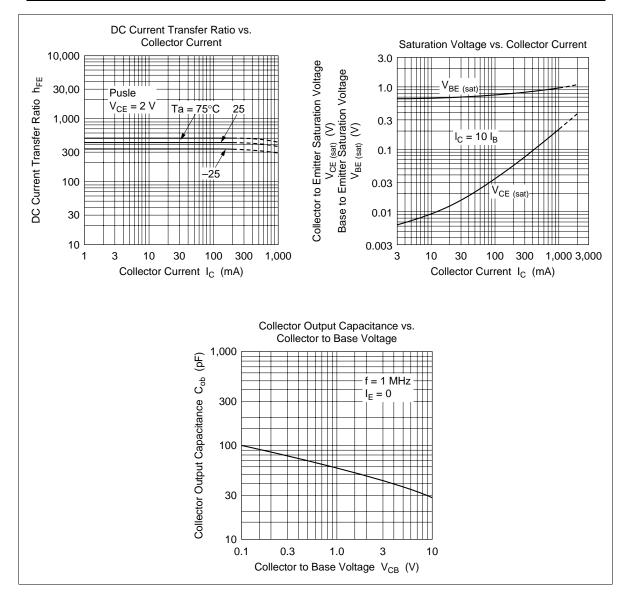
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{\rm (BR)CBO}$	20	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	16	—	—	V	I_{c} = 1 mA, R_{BE} = ∞
Emitter to base breakdown voltage	$V_{(BR)EBO}$	6	—	—	V	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	_	_	0.1	μΑ	$V_{CB} = 16 \text{ V}, I_{E} = 0$
Emitter cutoff current	I _{EBO}	_		0.1	μΑ	$V_{EB} = 5 V, I_{C} = 0$
DC current transfer ratio	h _{FE} *1	100		500		V_{ce} = 2 V, I_c = 0.1 A, Pulse
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	—	0.15	0.3	V	$I_{c} = 1 \text{ A}, I_{B} = 0.1 \text{ A}, \text{Pulse}$
Base to emitter saturation voltage	$V_{\text{BE(sat)}}$	—	0.9	1.2	V	$I_{c} = 1 \text{ A}, I_{B} = 0.1 \text{ A}, \text{Pulse}$
Gain bandwidth product	f _T	_	100	_	MHz	$V_{ce} = 2 \text{ V}, \text{ I}_{c} = 10 \text{ mA}$
Collector output capacitance	Cob	_	20	_	pF	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$
Note: 1. The 2SD1367 is gro	ouped by h	_{FE} as foll	ows.			
Mark BA BI	В	BC				

Mark	BA	BB	BC
h_{FE}	100 to 200	160 to 320	250 to 500

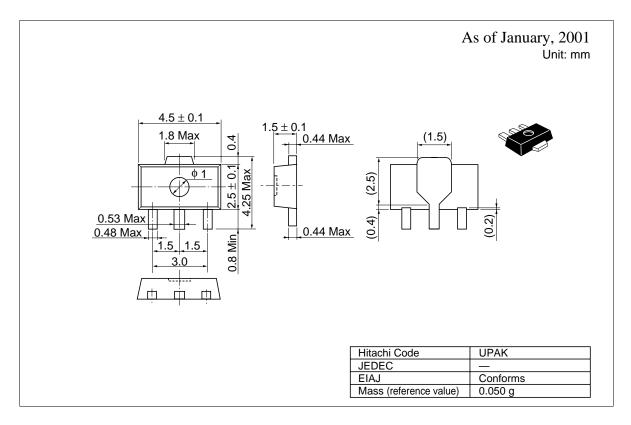
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Package Dimensions



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Hitachi, Ltd.

Semiconductor & Integrated Circuits. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL	NorthAmerica Europe		http://semiconductor.hitachi.com/ http://www.hitachi-eu.com/hel/ecg
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For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose,CA 95134
Tel: <1> (408) 433-1990
Fax: <1>(408) 433-0223

Hitachi Europe GmbH Electronic Components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd.

Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel : <886>-(2)-2718-3666 Tel: <44> (1628) 585000 Fax: <44> (1628) 585160

Hitachi Asia Ltd. Hitachi Tower 16 Collyer Quay #20-00, Singapore 049318 Tel : <65>-538-6533/538-8577 Fax : <65>-538-6933/538-3877 URL : http://www.hitachi.com.sg

Hitachi Asia Ltd (Taipei Branch Office) 4/F, No. 167, Tun Hwa North Road, Hung-Kuo Building. Taipei (105), Taiwan Fax : <886>-(2)-2718-8180 Telex : 23222 HAS-TP URL : http://www.hitachi.com.tw

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road Tsim Sha Tsui, Kowloon, Hong Kong Tel : <852>-(2)-735-9218 Fax : <852>-(2)-730-0281 URL : http://www.hitachi.com.hk

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